

Description

Title of Invention: SUPPORTING GLASS SUBSTRATE, LAMINATE, SEMICONDUCTOR PACKAGE, ELECTRONIC DEVICE, AND METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGE

Technical Field

[0001] The present invention relates to a supporting glass substrate and a laminate using the supporting glass substrate, and more specifically, to a supporting glass substrate to be used for supporting a processed substrate in a manufacturing process for a semiconductor package and a laminate using the supporting glass substrate.

Background Art

[0002] Portable electronic devices, e.g., a cellular phone, a notebook-size personal computer, and a personal data assistance (PDA), are required to be downsized and reduced in weight. Along with this, a mounting space for semiconductor chips to be used in those electronic devices is strictly limited, and there is a problem of high-density mounting of the semiconductor chips. In view of this, in recent years, there has been an attempt to perform high-density mounting of a semiconductor package by a three-dimensional mounting technology, that is, by laminating semiconductor chips on top of another and connecting the semiconductor chips through wiring.

[0003] A related-art wafer level package (WLP) is manufactured

modulus of 65 GPa or more.

[Claim 7] A laminate, comprising at least a processed substrate and a supporting glass substrate configured to support the processed substrate, the supporting glass substrate comprising the supporting glass substrate of any one of claims 1 to 6.

[Claim 8] The laminate according to claim 7, wherein the processed substrate comprises at least a semiconductor chip molded with a sealing material.

[Claim 9] A method of manufacturing a semiconductor package, comprising the steps of:

- preparing a laminate comprising at least a processed substrate and a supporting glass substrate configured to support the processed substrate;

- conveying the laminate; and

- subjecting the processed substrate to processing treatment, the supporting glass substrate comprising the supporting glass substrate of any one of claims 1 to 6.

[Claim 10] The method of manufacturing a semiconductor package according to claim 9, wherein the processing treatment comprises a step of arranging wiring on one surface of the processed substrate.